

# SN54BCT241, SN74BCT241 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS005D – OCTOBER 1987 – REVISED APRIL 1994

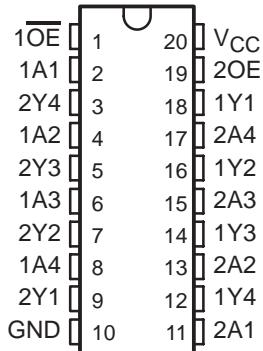
- State-of-the-Art BiCMOS Design Significantly Reduces  $I_{CCZ}$
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic and Ceramic 300-mil DIPs (J, N)

## description

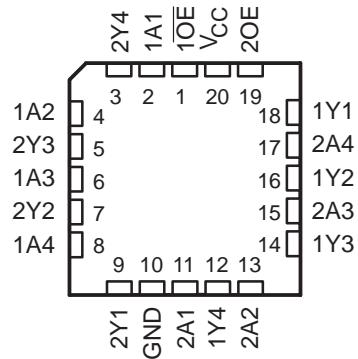
These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Taken together with the 'BCT240 and 'BCT244, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical  $\overline{OE}$  (active-low output-enable) inputs, and complementary OE and  $\overline{OE}$  inputs.

The SN54BCT241 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74BCT241 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54BCT241 . . . J OR W PACKAGE  
SN74BCT241 . . . DB, DW OR N PACKAGE  
(TOP VIEW)



SN54BCT241 . . . FK PACKAGE  
(TOP VIEW)



## FUNCTION TABLES

INPUTS		OUTPUT 1Y
1OE	1A	
L	H	H
L	L	L
H	X	Z

INPUTS		OUTPUT 2Y
2OE	2A	
H	H	H
H	L	L
L	X	Z

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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 **TEXAS  
INSTRUMENTS**

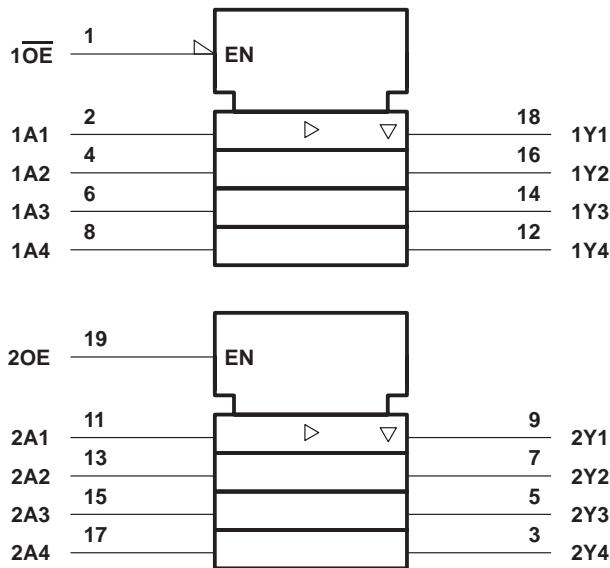
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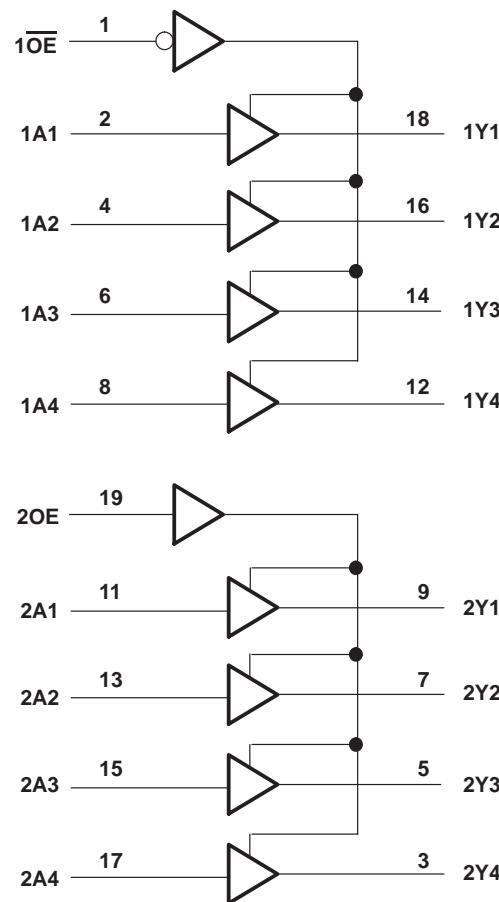
# SN54BCT241, SN74BCT241 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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## logic symbol†



## logic diagram (positive logic)



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡**

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

		SN54BCT241			SN74BCT241			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
I <sub>IK</sub>	Input clamp current			-18			-18	mA
I <sub>OH</sub>	High-level output current			-12			-15	mA
I <sub>OL</sub>	Low-level output current			48			64	mA
T <sub>A</sub>	Operating free-air temperature	-55	125	0	0	70		°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54BCT241			SN74BCT241			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = -18 mA			-1.2			-1.2	V
V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -3 mA	2.4	3.3	2.4	3.3		V
		I <sub>OH</sub> = -12 mA	2	3.2				
		I <sub>OH</sub> = -15 mA			2	3.1		
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA	0.38	0.55				V
		I <sub>OL</sub> = 64 mA			0.42	0.55		
I <sub>I</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 7 V			0.1			0.1	mA
I <sub>IH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 2.7 V			20			20	μA
I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V, Any A input	V <sub>I</sub> = 0.5 V		-1			-1	mA
				-1.6			-1.6	
I <sub>OZH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.7 V			50			50	μA
I <sub>OZL</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0.5 V			-50			-50	μA
I <sub>OS‡</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0		-100	-225	-100	-225		mA
I <sub>CCH</sub>	V <sub>CC</sub> = 5.5 V, Outputs open		23	43	23	43		mA
I <sub>CCL</sub>	V <sub>CC</sub> = 5.5 V, Outputs open		53	85	53	85		mA
I <sub>CCZ</sub>	V <sub>CC</sub> = 5.5 V, Outputs open		4	10	4	10		mA
C <sub>i</sub>	V <sub>CC</sub> = 5 V, V <sub>I</sub> = 2.5 V or 0.5 V		6		6			pF
C <sub>o</sub>	V <sub>CC</sub> = 5 V, V <sub>O</sub> = 2.5 V or 0.5 V		11		11			pF

† All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

**SN54BCT241, SN74BCT241  
OCTAL BUFFERS/DRIVERS  
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**switching characteristics (see Note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, C <sub>L</sub> = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T <sub>A</sub> = 25°C			V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T <sub>A</sub> = MIN to MAX†			UNIT	
			'BCT241			SN54BCT241		SN74BCT241		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	0.5	2.5	4.5	0.5	5.2	0.5	4.9	ns
t <sub>PHL</sub>			1	3	5.4	1	6.3	1	5.9	
t <sub>PZH</sub>	$\overline{OE}$ or OE	Y	1	5.7	7.8	1	9.1	1	8.7	ns
t <sub>PZL</sub>			1	5.2	8.6	1	10	1	9.4	
t <sub>PHZ</sub>	$\overline{OE}$ or OE	Y	1	5.8	6.8	1	8.4	1	8.1	ns
t <sub>PLZ</sub>			1	7	8.1	1	11	1	9.9	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



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## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9074301M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9074301M2A SNJ54BCT241FK	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
5962-9074301MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9074301MR A SNJ54BCT241J	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
5962-9074301MSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9074301MS A SNJ54BCT241W	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74BCT241DBLE	OBsolete	SSOP	DB	20		TBD	Call TI	Call TI	0 to 70		
SN74BCT241N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74BCT241N	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74BCT241NSR	OBsolete	SO	NS	20		TBD	Call TI	Call TI	0 to 70	BCT241	
SN74BCT241NSRE4	OBsolete	SO	NS	20		TBD	Call TI	Call TI	0 to 70		
SN74BCT241NSRG4	OBsolete	SO	NS	20		TBD	Call TI	Call TI	0 to 70		
SNJ54BCT241FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9074301M2A SNJ54BCT241FK	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SNJ54BCT241J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9074301MR A SNJ54BCT241J	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SNJ54BCT241W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9074301MS A SNJ54BCT241W	<span style="background-color: red; color: white; padding: 2px;">Samples</span>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54BCT241, SN74BCT241 :**

- Catalog: [SN74BCT241](#)
- Military: [SN54BCT241](#)

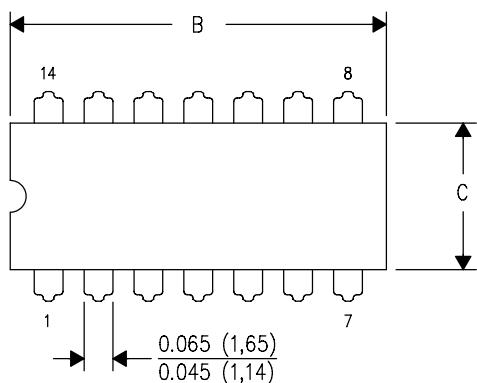
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

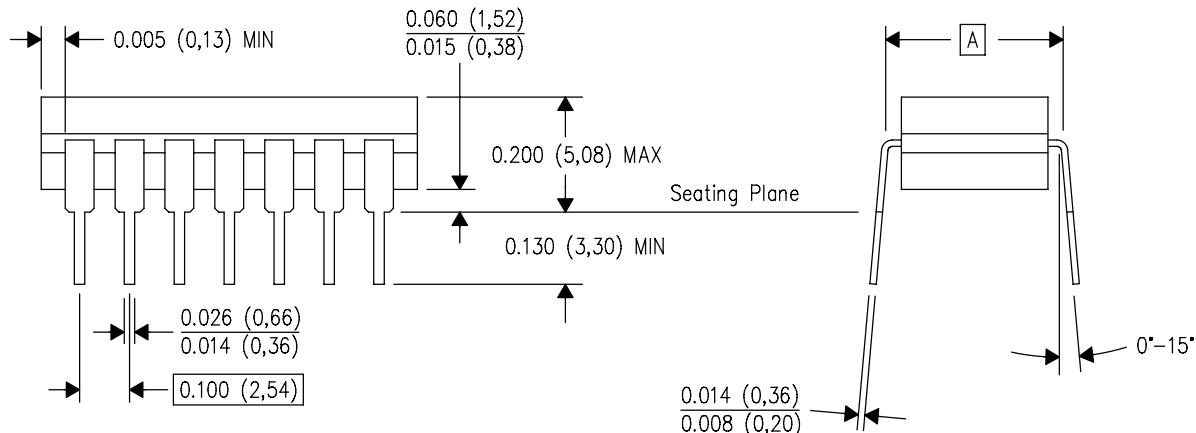
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

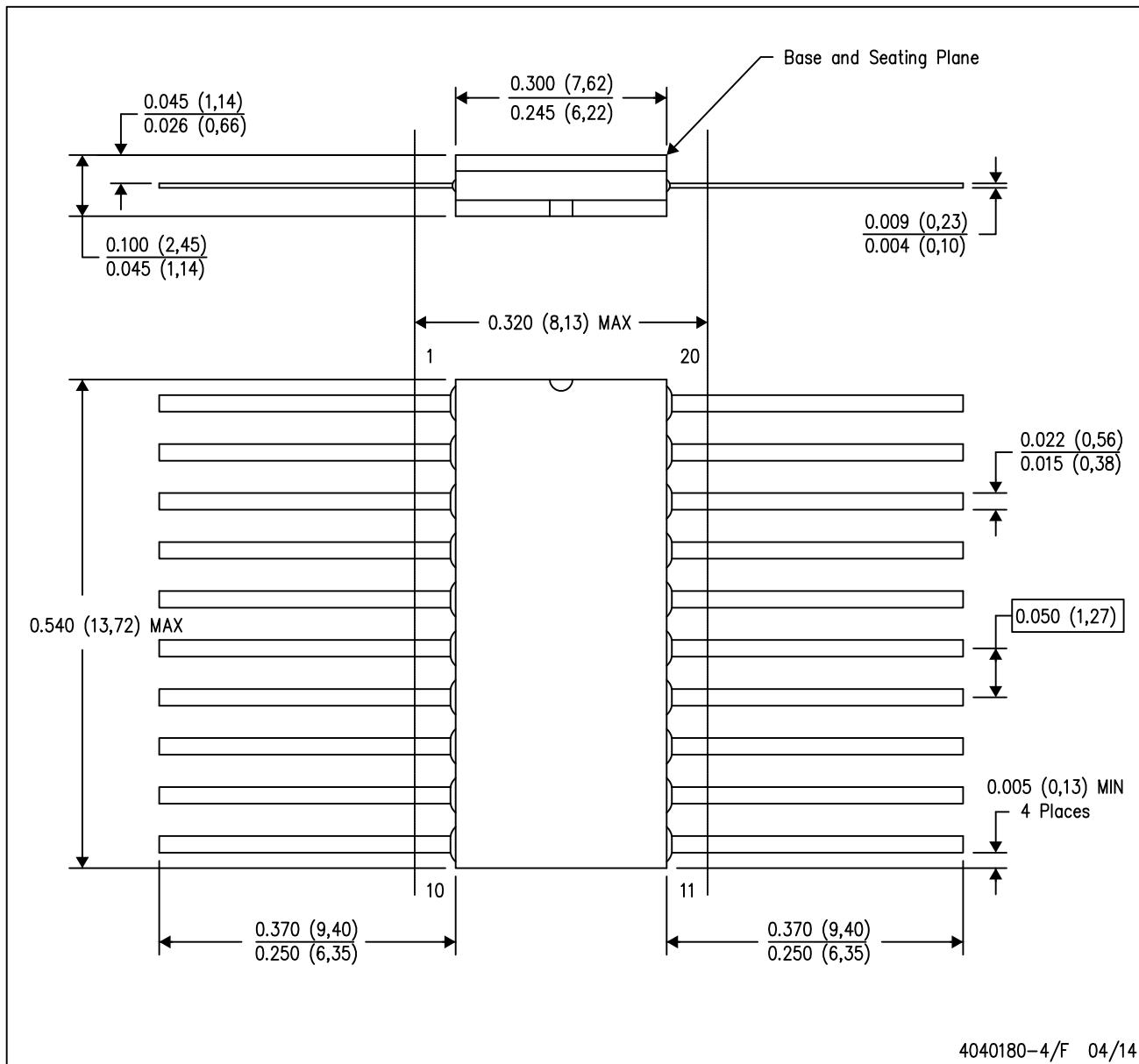


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. This package is hermetically sealed with a ceramic lid using glass frit.  
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



4040180-4/F 04/14

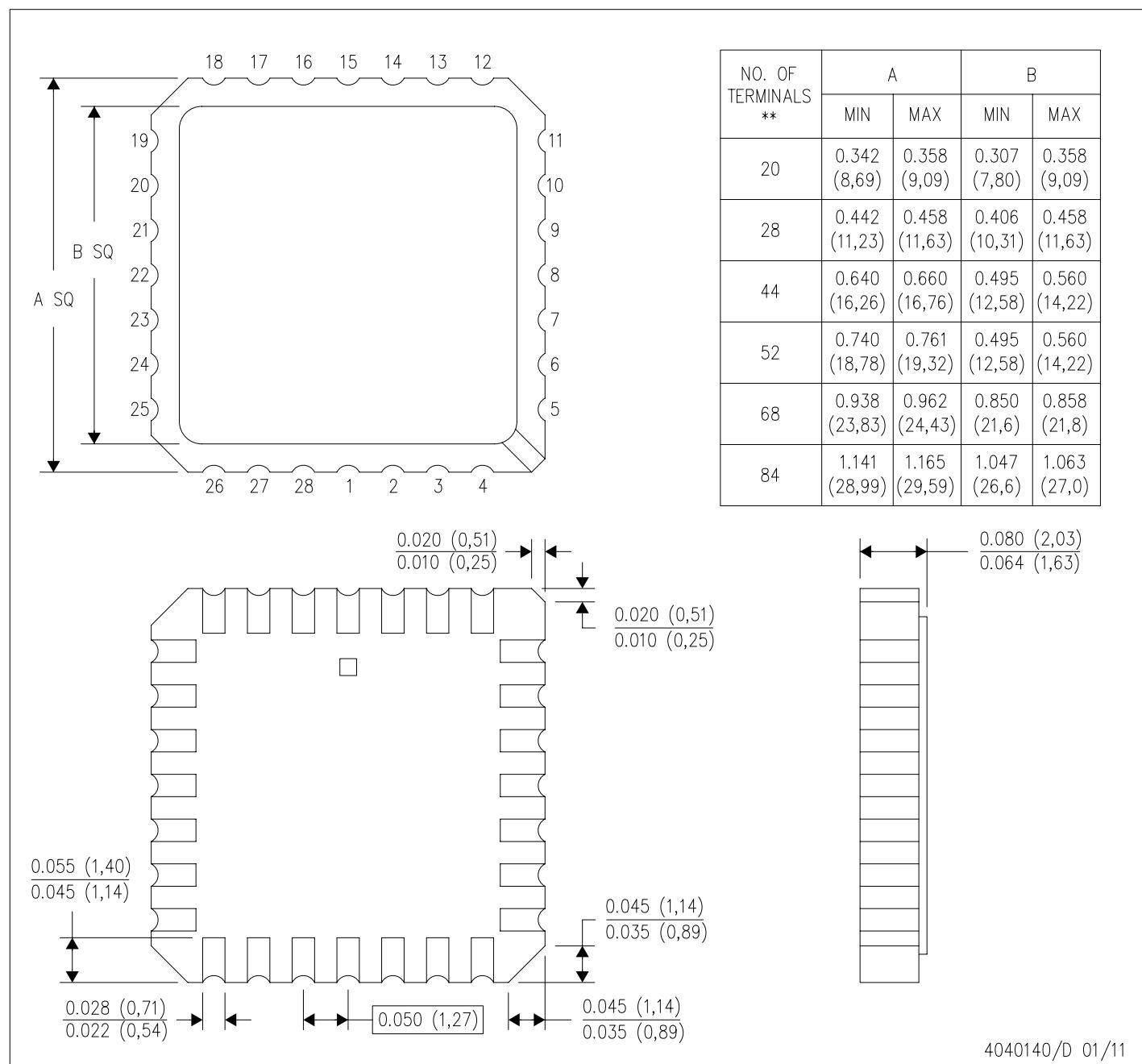
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

4040140/D 01/11

## N (R-PDIP-T\*\*)

16 PINS SHOWN

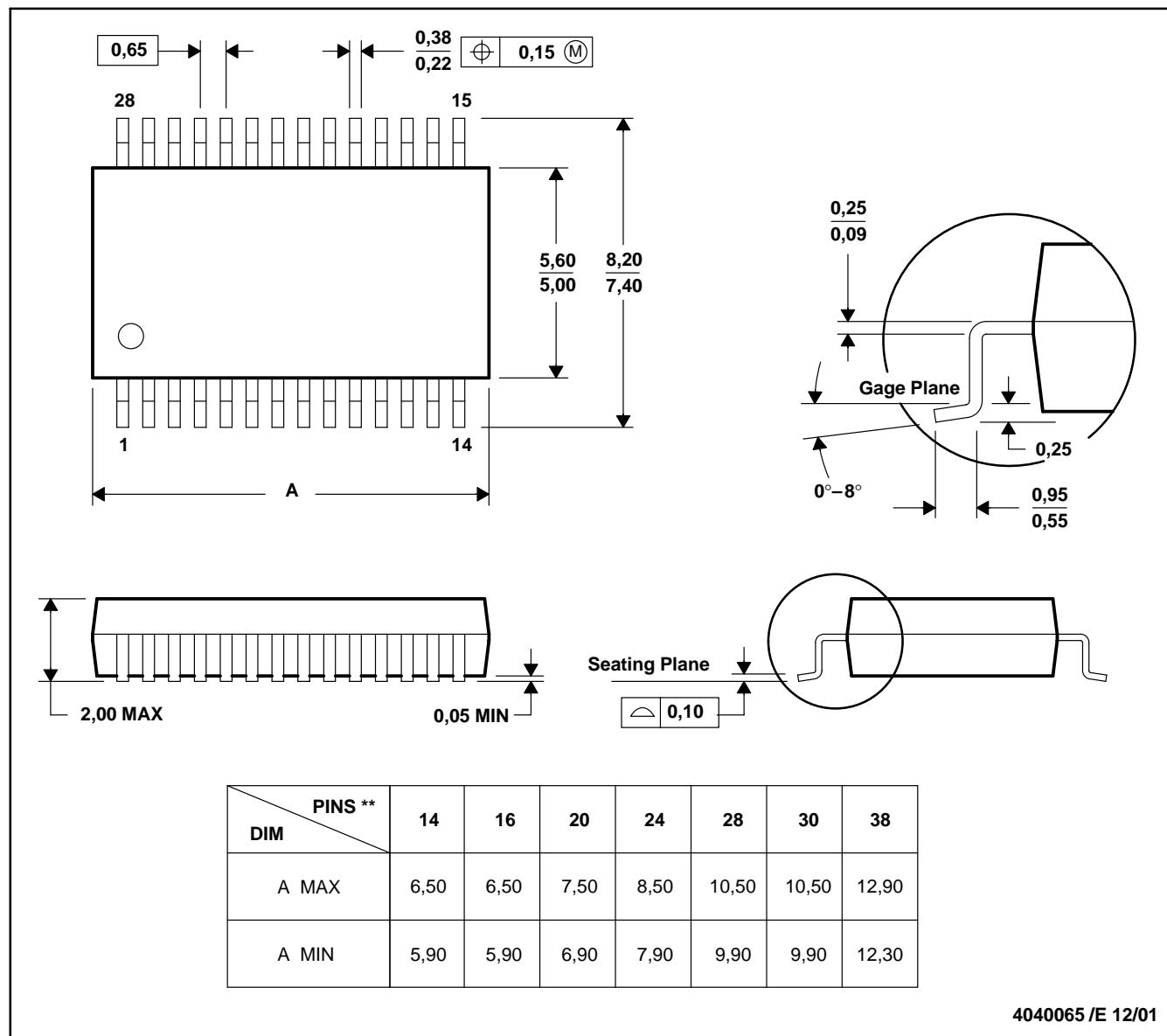
## PLASTIC DUAL-IN-LINE PACKAGE



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



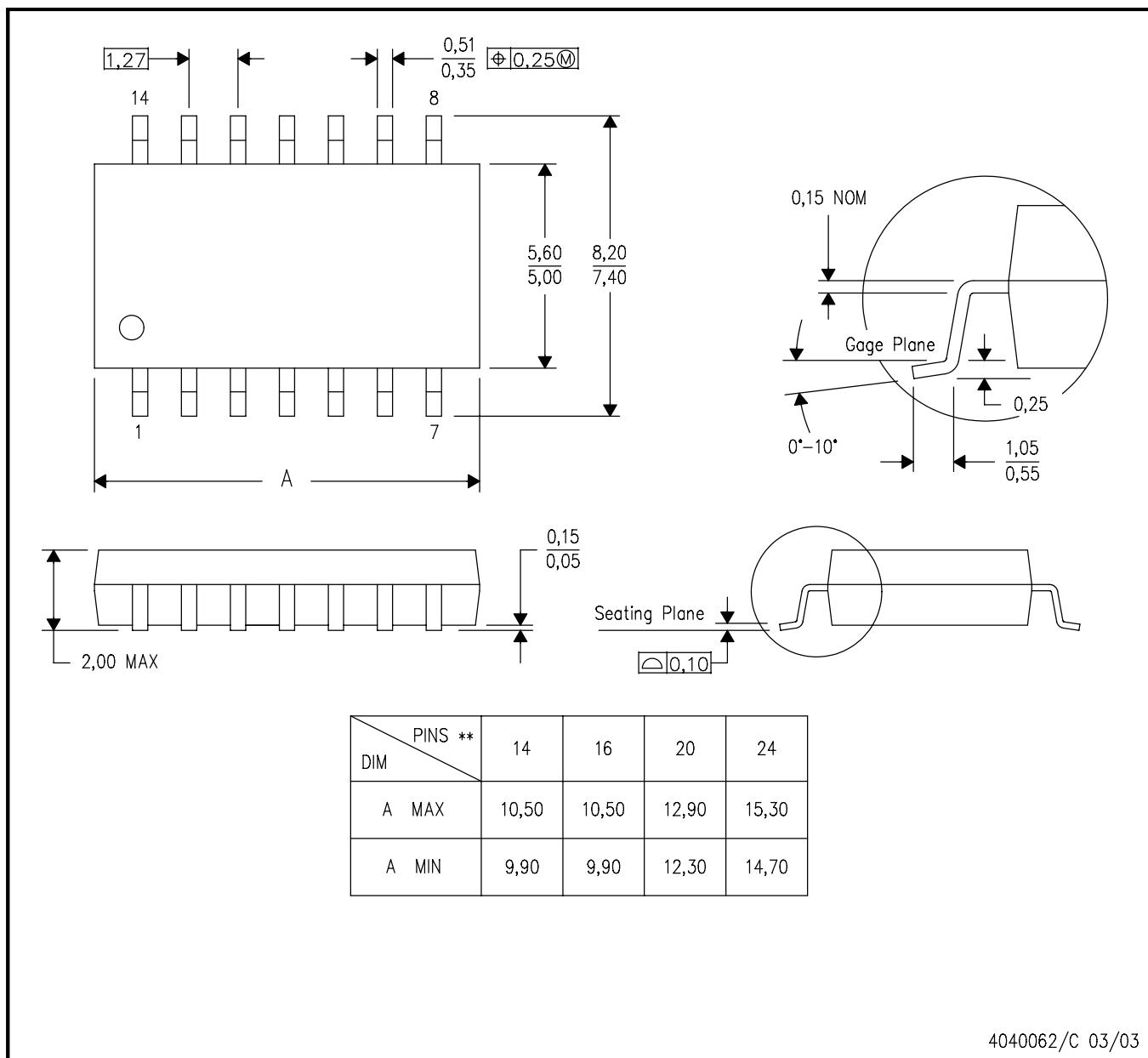
NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## MECHANICAL DATA

NS (R-PDSO-G\*\*)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

4040062/C 03/03

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